

Industry Leading Epoxy Laminate and Prepreg
Tg 180°C Td 340°C Dk 4.04 Df 0.021

# 370HR is the industry's "best in class" lead-free compatible product for high-reliability applications across a wide range of markets.

### **PRODUCT FEATURES**

**Industry Recognition** 

- UL File Number: E41625
- Polyclad<sup>®</sup> Grade PCL-FR-370HR
- Qualified to UL's MCIL Program
- RoHS Compliant

Performance Attributes

CAF resistant

Processing Advantages

- FR-4 process compatible
- UV blocking and AOI fluorescence
- Multiple reflow capable
- HDI technology compatible

### **PRODUCT AVAILABILITY**

Standard Material Offering: Laminate

• 2 to 125 mil (0.05 to 3.2 mm)

Copper Foil Type

- HTE Grade 3
- RTF (Reverse Treat Foil)
- Embedded resistor foil

### Copper Weight

- $^{\bullet}$  ½, 1 and 2 oz (18, 35 and 70  $\mu m)$  available
- Heavier copper foil available
- Thinner copper foil available

Standard Material Offering: Prepreg

Tooling of prepreg panels

Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass

# ORDERING INFORMATION:

Contact your local sales representative or contact <a href="mailto:info@isola-group.com">info@isola-group.com</a> for further information.

370HR laminates and prepregs, deigned by Polyclad, are made using a patented high performance 180°C Tg FR-4 multifunctional epoxy resin system that is designed for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required. We manufacture 370HR laminates and prepregs with high quality E-glass glass fabric for superior Conductive Anodic Filament (CAF) resistance. 370HR provides superior thermal performance with low Coefficient of Thermal Expansion (CTE) and the mechanical, chemical and moisture resistance properties that equal or exceed the performance of traditional FR-4 materials.

370HR is used in thousands of PWB designs and has proven to be best in class for thermal reliability, CAF performance, ease of processing and proven performance on seguential lamination designs.

### PRODUCT ATTRIBUTES





### TYPICAL MARKET APPLICATIONS













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# **Typical Values Table**

			Units	Test Method
	Property	Typical Value	Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss		340	°C	2.4.24.6
Time to Delaminate by TMA	A. T260	60		
(Copper removed)	B. T288	30	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg	45	ppm/°C ppm/°C %	2.4.24C
	B. Post-Tg	230		
	C. 50 to 260°C, (Total Expansion)	2.8		
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/m·K	ASTM E1952
Thermal Stress 10 sec @	A. Unetched	Pass	Pass Visual	2.4.13.1
288ºC (550.4ºF)	B. Etched	1 433	1 433 13441	2.7.13.1
Dk, Permittivity	A. @ 100 MHz	4.24	_	2.5.5.3
	B. @ 1 GHz	4.17		2.5.5.9
	C. @ 2 GHz	4.04		Bereskin Stripline
	D. @ 5 GHz	3.92		Bereskin Stripline
	E. @ 10 GHz	3.92		Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz	0.0150		2.5.5.3
	B. @ 1 GHz	0.0161	_	2.5.5.9
	C. @ 2 GHz	0.0210	_	Bereskin Stripline
	D. @ 5 GHz	0.0250	_	2.5.5.5
	E. @ 10 GHz	0.0250		2.5.5.5
Volume Resistivity	A. After moisture resistance	$3.0 \times 10^8$ $7.0 \times 10^8$	MΩ-cm	2.5.17.1
	B. At elevated temperature	$3.0 \times 10^6$		
Surface Resistivity	A. After moisture resistance B. At elevated temperature	2.0 x 10 <sup>8</sup>	ΜΩ	2.5.17.1
Dielectric Breakdown		>50	kV	2.5.6B
Arc Resistance		115	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		54 (1350)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile		N/mm (lb/inch)	2.4.00
	copper foil all copper foil >17 μm [0.669 mil]	1.14 (6.5)		2.4.8C
	B. Standard profile copper	1.25 (7.0)		2.4.8.2A
	1. After thermal stress	1.25 (7.0)		2.4.8.3
	2. At 125°C (257°F)	1.25 (7.0) 1.14 (6.5)		2.4.8.3
	3. After process solutions			
Flexural Strength	A. Length direction B. Cross direction	6201 (90.0)	MPa (kpsi)	2.4.4B
		531 (77.0)		
Tensile Strength	A. Length direction B. Cross direction	385 (55.9) 245 (35.6)	MPa (kpsi)	ASTM D3039
Young's Modulus	A. Length direction	3744	ksi	ASTM D790-15e2
	B. Cross direction	3178		
Poisson's Ratio	A. Length direction	0.177		
	B. Cross direction	0.171	_	ASTM D3039
Moisture Absorption		0.15	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94

### **NOTES**

Visit our site <a href="http://www.isola-group.com">http://www.isola-group.com</a> for more details.

Revisions:

A: Initial release - 4/17

B: Corrected units for Flexural and Tensile Strength - 8/18

C: Change MOT to RTI 5/19

D: Changed VLP2 to HVLP to align with common industry terms 4/21

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